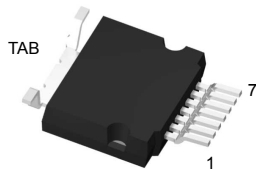
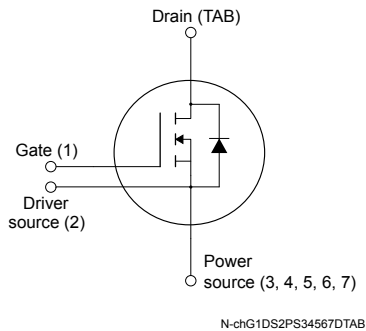


Automotive-grade silicon carbide Power MOSFET 750 V, 11.4 mΩ typ., 110 A in an HU3PAK package



HU3PAK



Product status link

[SCT011HU75G3AG](#)

Product summary

Order code	SCT011HU75G3AG
Top-side marking	11HU75G3AG
Back-side marking	SCT11HU75G3A
Package	HU3PAK
Packing	Tape and reel

Features

Order code	V _{DS}	R _{DS(on)} typ.	I _D
SCT011HU75G3AG	750 V	11.4 mΩ	110 A

- AEC-Q101 qualified 
- Very low R_{DS(on)} over the entire temperature range
- High speed switching performances
- Very fast and robust intrinsic body diode
- Source sensing pin for increased efficiency

Applications

- DC/DC converter for EV/HEV
- Main inverter (electric traction)
- On board charger (OBC)

Description

This silicon carbide Power MOSFET device has been developed using ST's advanced and innovative 3rd generation SiC MOSFET technology. The device features a very low R_{DS(on)} over the entire temperature range combined with low capacitances and very high switching operations, which improve application performance in frequency, energy efficiency, system size and weight reduction.

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	750	V
V_{GS}	Gate-source voltage	-10 to 22	V
	Gate-source voltage (recommended operating values)	-5 to 18	
	Gate-source transient voltage, $t_p < 1 \mu s$, $t \leq 10$ hours over lifetime	-11 to 25	
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ C$	110	A
	Drain current (continuous) at $T_C = 100^\circ C$	110	
$I_{DM}^{(2)}$	Drain current (pulsed)	532	A
P_{TOT}	Total power dissipation at $T_C = 25^\circ C$	652	W
T_{stg}	Storage temperature range	-55 to 175	$^\circ C$
T_J	Operating junction temperature range		$^\circ C$

1. Limited by bonding wires.

2. Pulse width is limited by safe operating area.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	0.23	$^\circ C/W$
R_{thJA}	Thermal resistance, junction-to-ambient	50	$^\circ C/W$

2 Electrical characteristics

$T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	750			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 750\text{ V}$			10	μA
I_{GSS}	Gate-body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = -10\text{ to }22\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 1\text{ mA}$	1.8	3.2	4.2	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 18\text{ V}$, $I_D = 80\text{ A}$		11.4	15	m Ω
		$V_{GS} = 15\text{ V}$, $I_D = 80\text{ A}$		14.2		
		$V_{GS} = 18\text{ V}$, $I_D = 80\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$		17.1		
		$V_{GS} = 15\text{ V}$, $I_D = 80\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$		18.9		

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 400\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	3860	-	pF
C_{oss}	Output capacitance		-	300	-	pF
C_{rss}	Reverse transfer capacitance		-	31	-	pF
Q_g	Total gate charge	$V_{DD} = 400\text{ V}$, $V_{GS} = -5\text{ to }18\text{ V}$, $I_D = 50\text{ A}$	-	154	-	nC
Q_{gs}	Gate-source charge		-	53.5	-	nC
Q_{gd}	Gate-drain charge		-	38	-	nC
R_g	Gate input resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	1.2	-	Ω

Table 5. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{on}	Turn-on switching energy	$V_{DD} = 400\text{ V}$, $I_D = 50\text{ A}$,	-	184	-	μJ
E_{off}	Turn-off switching energy	$R_G = 2.2\text{ }\Omega$, $V_{GS} = -5\text{ to }18\text{ V}$	-	114	-	μJ

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400\text{ V}$, $I_D = 50\text{ A}$, $R_G = 2.2\text{ }\Omega$, $V_{GS} = -5\text{ to }18\text{ V}$	-	23	-	ns
t_r	Rise time		-	11	-	ns
$t_{d(off)}$	Turn-off delay time		-	42	-	ns
t_f	Fall time		-	9	-	ns

Table 7. Reverse SiC diode characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)}$	Continuous diode forward current	$T_C = 25\text{ }^{\circ}\text{C}$	-		110	A
		$T_C = 100\text{ }^{\circ}\text{C}$	-		110	
V_{SD}	Diode forward voltage	$I_{SD} = 50\text{ A}$, $V_{GS} = 0\text{ V}$	-	2.6		V
t_{rr}	Reverse recovery time	$I_{SD} = 50\text{ A}$, $di/dt = 1\text{ kA}/\mu\text{s}$, $V_{DD} = 400\text{ V}$, $V_{GS} = -5\text{ V}$	-	22		ns
Q_{rr}	Reverse recovery charge		-	186		nC
I_{RRM}	Reverse recovery current		-	14		A

1. Limited by bonding wires.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

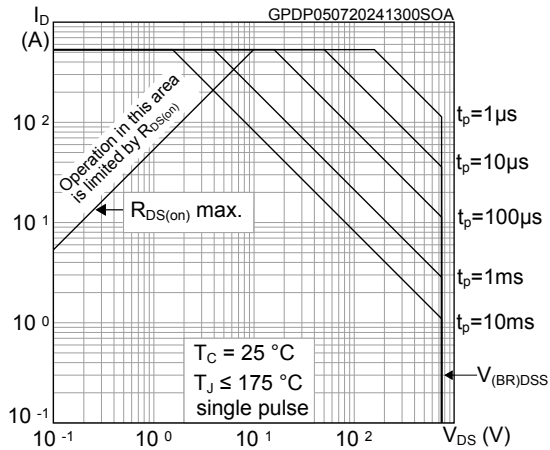


Figure 2. Maximum transient thermal impedance

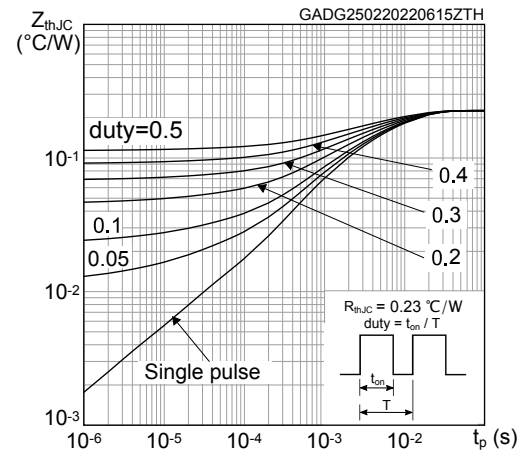


Figure 3. Typical output characteristics ($T_J = 25\text{ °C}$)

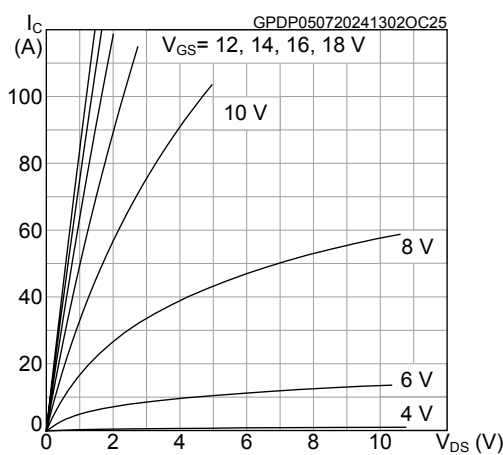


Figure 4. Typical output characteristics ($T_J = 175\text{ °C}$)

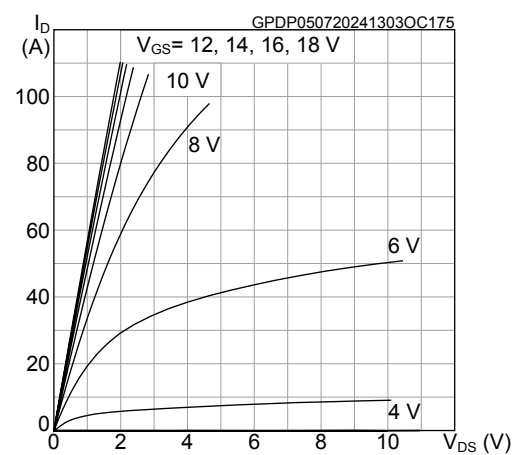


Figure 5. Typical transfer characteristics

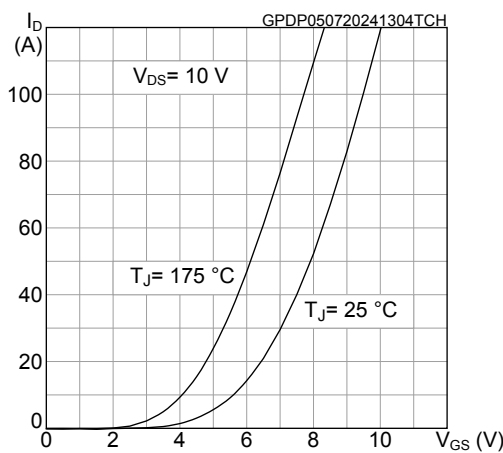


Figure 6. Total power dissipation

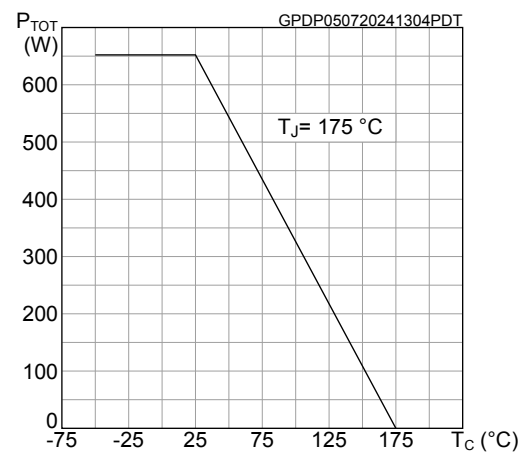


Figure 7. Maximum continuous drain current vs case temperature

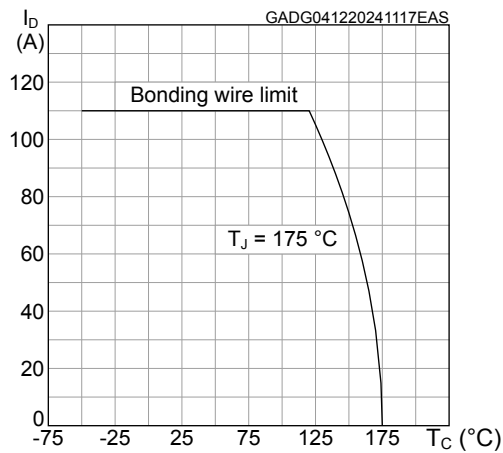


Figure 8. Normalized breakdown voltage vs temperature

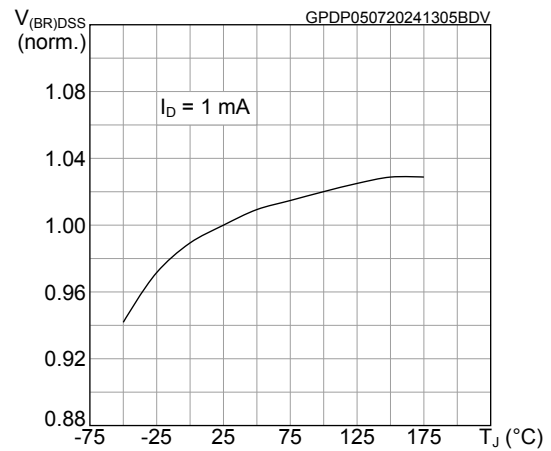


Figure 9. Normalized gate threshold vs temperature

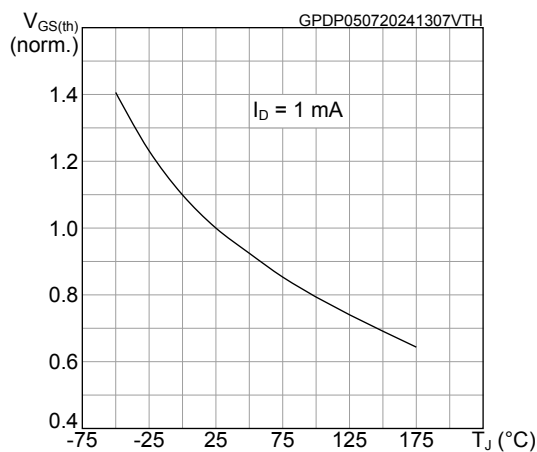


Figure 10. Normalized on-resistance vs temperature

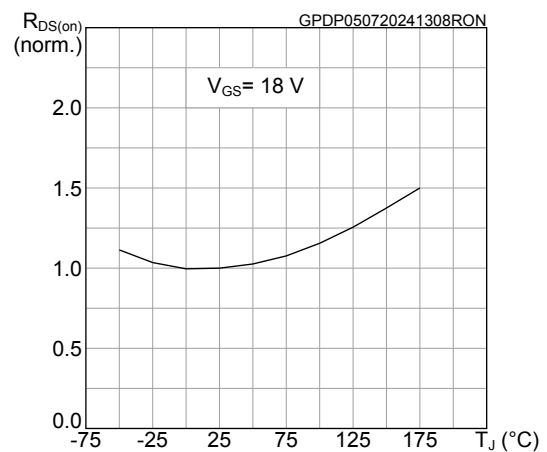


Figure 11. Typical reverse diode characteristics (Tj = 25 °C)

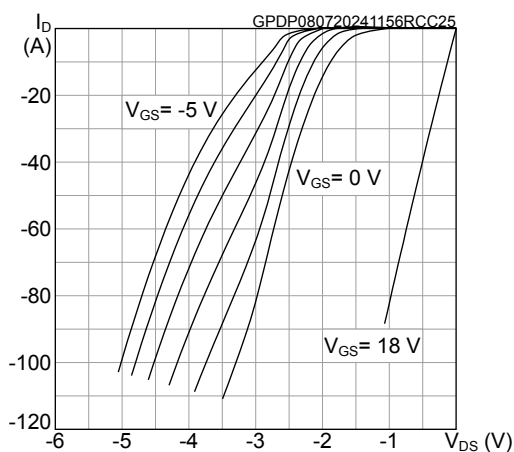


Figure 12. Typical reverse diode characteristics (Tj = 175 °C)

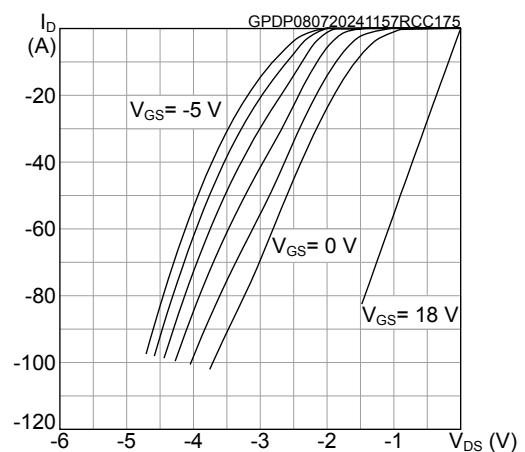
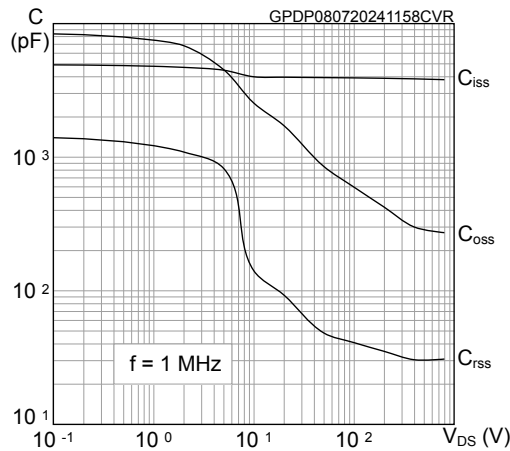
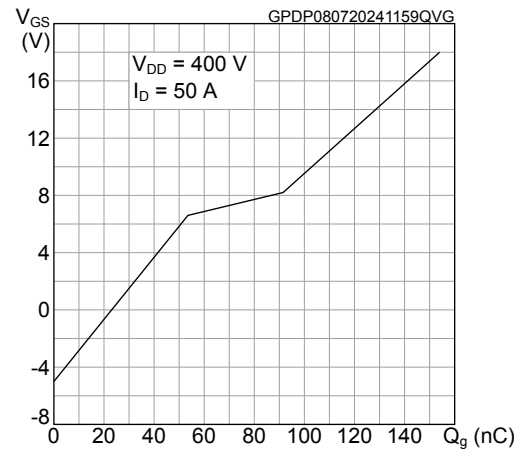
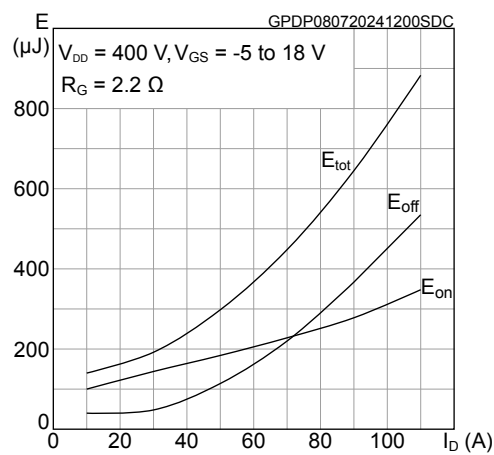
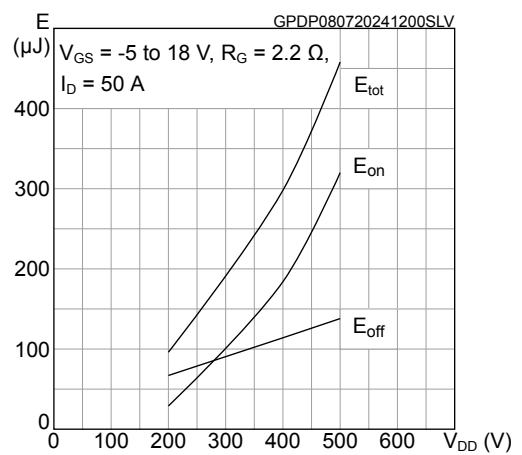
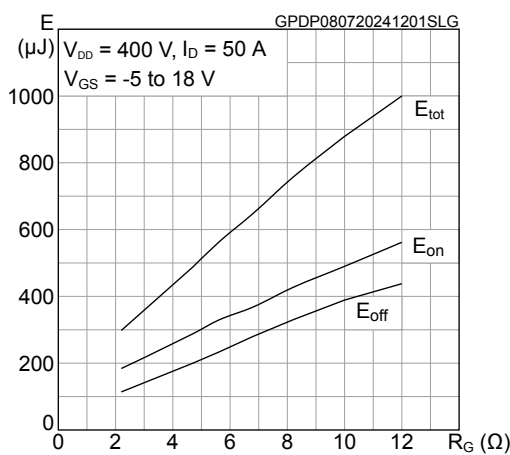
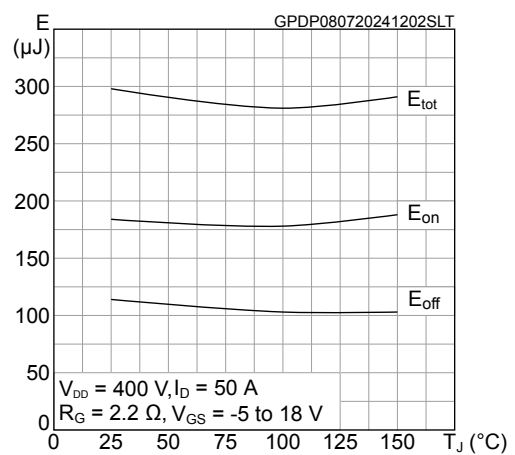


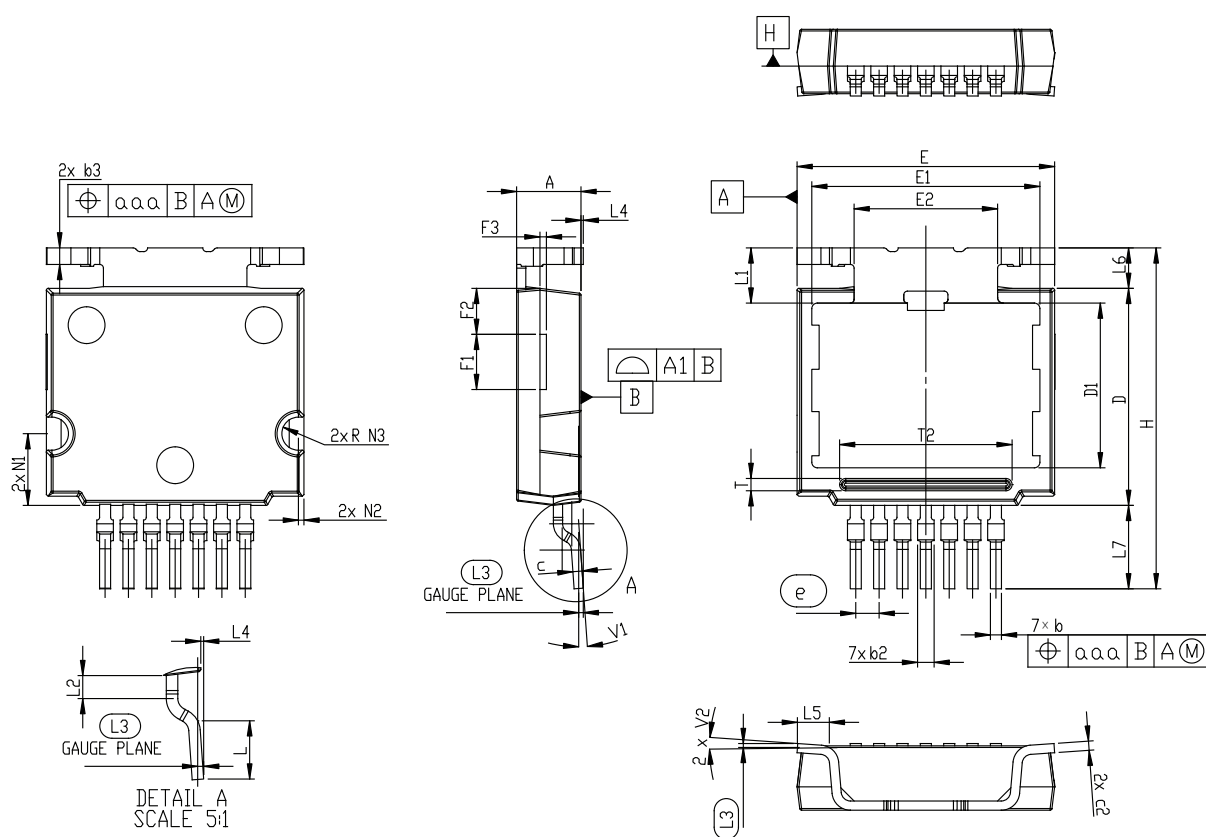
Figure 13. Typical capacitance characteristics

Figure 14. Typical gate charge characteristics

Figure 15. Typical switching energy vs drain current

Figure 16. Typical switching energy vs supply voltage

Figure 17. Typical switching energy vs gate resistance

Figure 18. Typical switching energy vs temperature


3 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 HU3PAK package information

Figure 19. HU3PAK package outline

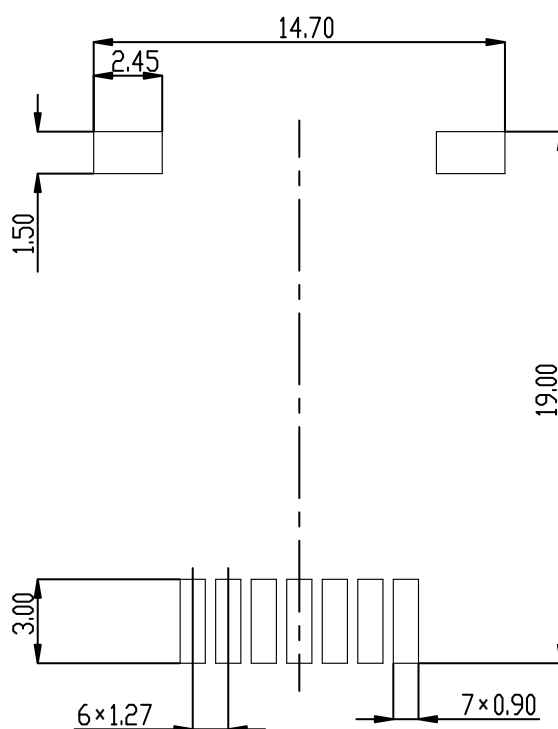


DM00674007 2

Table 8. HU3PAK package mechanical data

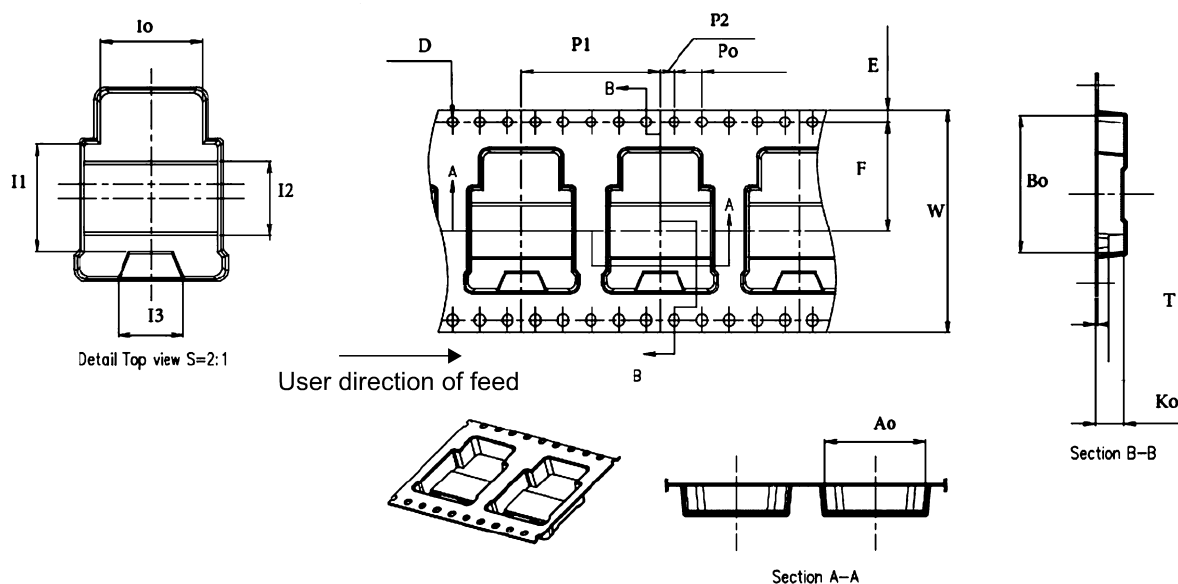
Ref.	Dimensions		
	mm		
	Min.	Typ.	Max.
A	3.40	3.50	3.60
A1		0.05	
b	0.50	0.60	0.70
b2	0.50	0.70	1.00
b3	0.80	0.90	1.00
c	0.40	0.50	0.60
c2	0.40	0.50	0.60
D	11.70	11.80	11.90
D1	8.80	8.955	9.10
E	13.90	14.00	14.10
E1	12.30	12.40	12.50
E2	7.75	7.80	7.85
e		1.27	
H	18.00	18.58	19.00
aaa		0.10	
L	2.40	2.52	2.60
L1		3.05	
L2	0.90	1.00	1.10
L3		0.26	
L4	0.075	0.125	0.175
L5	1.83	1.93	2.03
L6	2.14	2.24	2.34
L7	4.44	4.54	4.64
F1	2.90	3.00	3.10
F2	2.40	2.50	2.60
F3	0.25	0.35	0.45
N1	3.80	3.90	4.00
N2	0.25	0.30	0.45
N3	0.80	0.90	1.00
T	0.50	0.67	0.70
T2	9.18	9.38	9.43
V1		0 °	8 °
V2		0 °	8 °

Figure 20. HU3PAK recommended footprint (dimensions in mm)



3.2 HU3PAK packing information

Figure 21. HU3PAK carrier tape outline

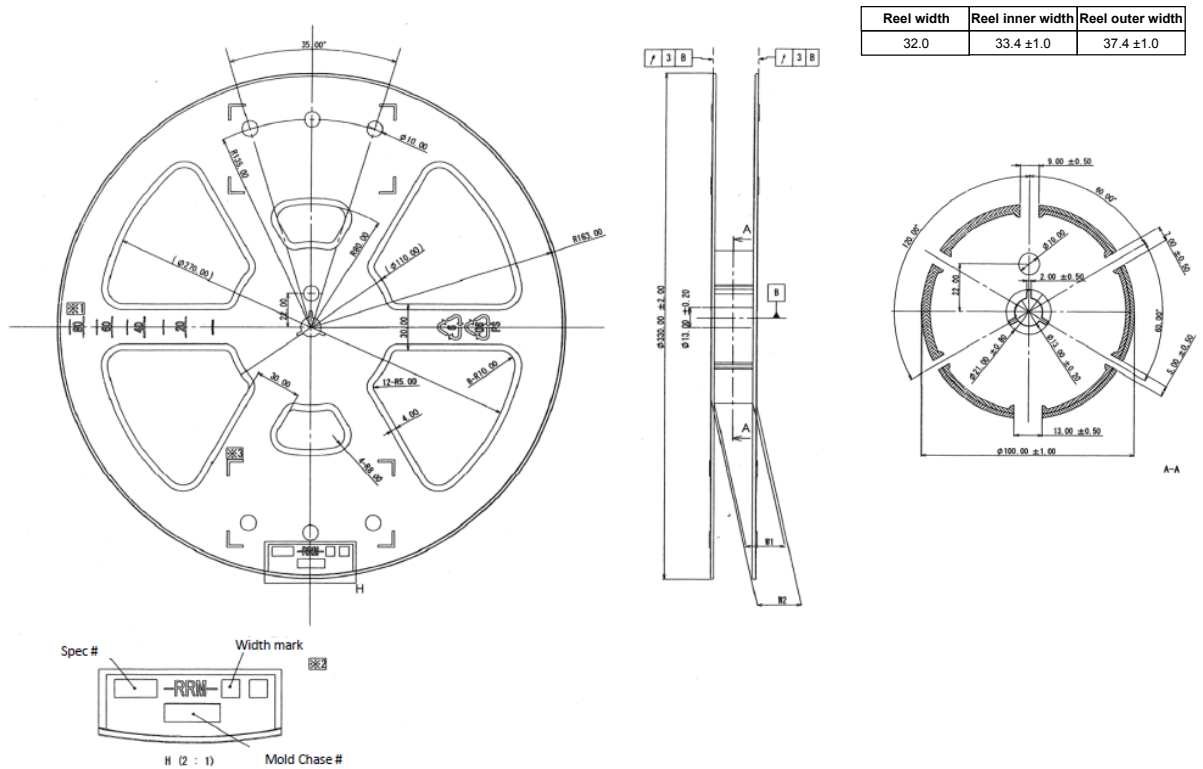


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Table 9. HU3PAK tape mechanical data

Dimension	Value
	mm
A0	14.40 ±0.10
B0	19.70
D	1.50 ±0.10
E	1.75 ±0.10
F	15.65 ±0.10
I0	11.00
I1	11.60 ±0.10
I2	8.00
I3	7.00
K0	4.20
P0	4.00 ±0.10
P1	20.00 ±0.10
P2	2.00 ±0.10
T	0.40 ±0.50
W	32.00 ±0.30

Figure 22. HU3PAK reel outline (dimensions are in mm)



DM00345054_3_reel

Revision history

Table 10. Document revision history

Date	Revision	Changes
19-Apr-2022	1	First release.
12-Jul-2024	2	Modified Table 1. Absolute maximum ratings , Table 3. On/off states , Table 4. Dynamic , Table 5. Switching energy (inductive load) , Table 6. Switching times and Table 7. Reverse SiC diode characteristics . Updated Section 2.1: Electrical characteristics (curves) . Minor text changes.
11-Dec-2024	3	Updated Section Device summary on cover page. Added Figure 7. Maximum continuous drain current vs case temperature . Minor text changes.



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